





Storage Temperature	T_{stg}	-55~+125	
Soldering Temperature	T_{sol}	260	

NOTE1: 100 μ s pulse, 100Hz frequency

NOTE2: AC for 1minute, R.H.=40~60%

ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Input	Forward Voltage	V_F	$I_F=10mA$	-	1.2	1.5	V
	Reverse Current	I_R	$V_R=6V$	-	-	1	μA
	Terminal Capacitance	C_t	$V=0$, $f=1MHz$	-	10	-	pF
Output	Collector-Emitter dark current	I_{CEO}	$V_{CE}=200V$, $I_F=0$	-	-	200	nA
	Collector-Emitter breakdown voltage	BV_{CEO}	$I_C=0.1mA$ $I_F=0$	300	-	-	V
	Emitter-Collector breakdown voltage	BV_{ECO}	$I_E=0.1mA$ $I_F=0$	0.3	-	-	V
Transfer Characteristics	Current transfer ratio	CTR	$I_F=1mA$ $V_{CE}=2V$	1000	-	7500	%
	Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_F=10mA$ $I_C=1mA$	-	-	1	V
	Isolation resistance	R_{IO}	DC500V 40~60%R.H.	10^{12}	-	-	Ω
	Floating Capacitance	C_{IO}	$V=0$, $f=1MHz$	-	0.8	-	pF
	Rise Time	t_r	$V_{CE}=10V$, $I_C=10mA$ $R_L=100\Omega$	-	40	-	μs
	Fall Time	t_f		-	15	-	μs
	Response Time	t_{on}		-	50	-	μs
		t_{off}		-	15	-	μs

NOTE1: Rank Table of Current Transfer Ratio (Temperature=25°C)

J	$I_F=140\mu A$, $V_{CE}=2V$	-	110
	$I_F=290\mu A$, $V_{CE}=2V$	450	-
	$I_F=1mA$, $V_{CE}=2V$	1000	7500
K	$I_F=1mA$, $V_{CE}=2V$	1000	7500
L	$I_F=1mA$, $V_{CE}=1V$	2000	7500

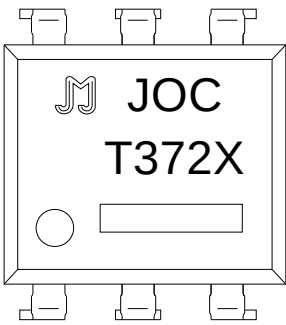


ORDERING INFORMATION

<u>J</u>	<u>OC</u>	<u>T</u>	<u>372</u>	<u>J</u>	<u>-D6P/S</u>	<u>/</u>
JieJie Microelectronics Co., Ltd.	Opto Coupler	Darlington Transistor	Marketization Model	CTR Rank:J/K/L	P:DIP6 S:SMD6	S:T3 L:T4

Packing Quantity			
Option	Quantity	Quantity – Inner box	Quantity –Outer box
DIP	60 Units/Tube	40 Tubes/Inner box	5 Inner box/Outer box =12k Units
SMD	1200 Units/Reel	2 Reels/Inner box	5 Inner box/Outer box =12k Units

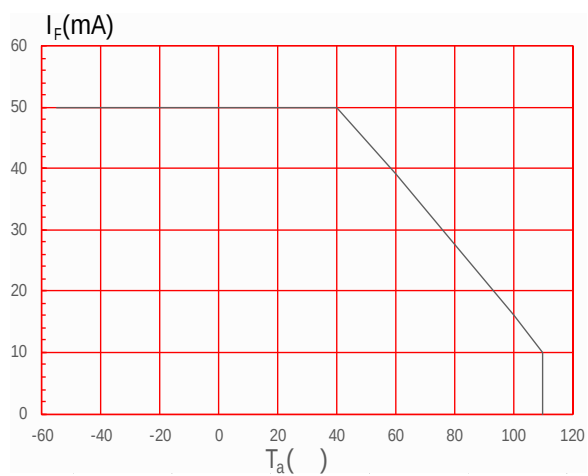
MARKING

	 Production Information Code
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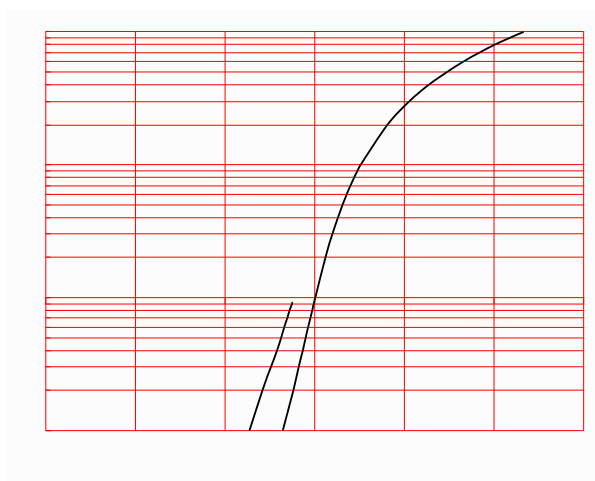


Characteristics Curves

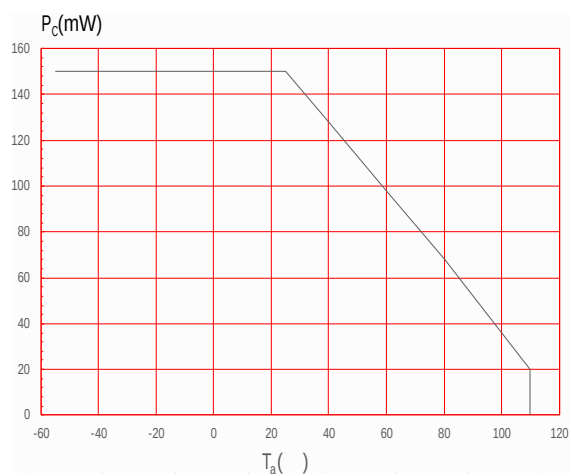
Max. Allowable LED Forward Current vs. Ambient Temperature



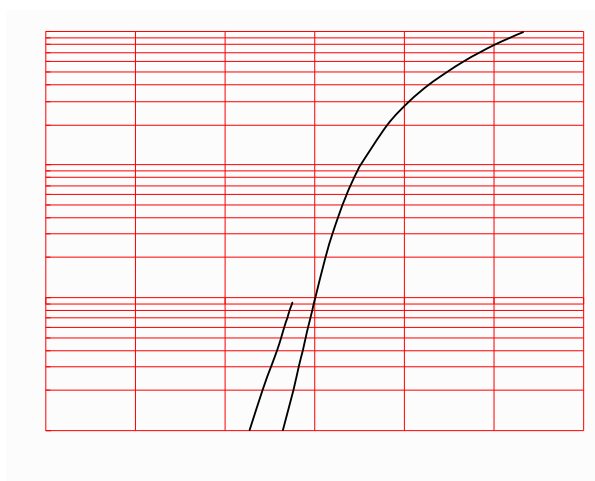
Forward Current vs. Forward Voltage



Collector Power Dissipation vs. Ambient Temperature

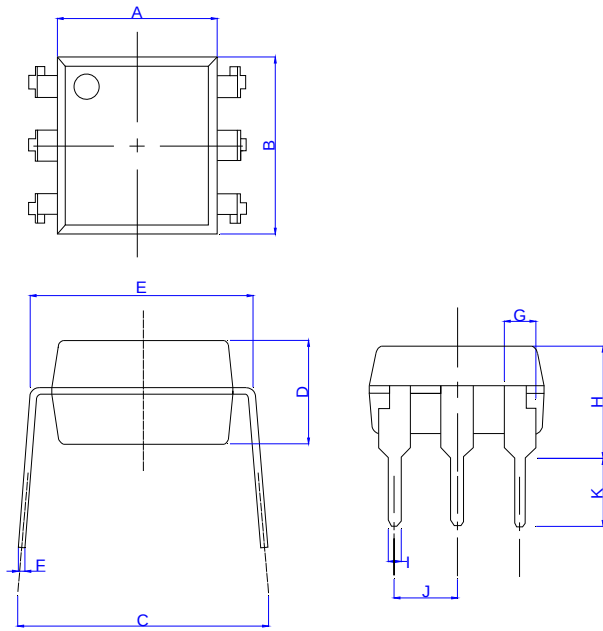


Collector Dark Current vs. Ambient Temperature

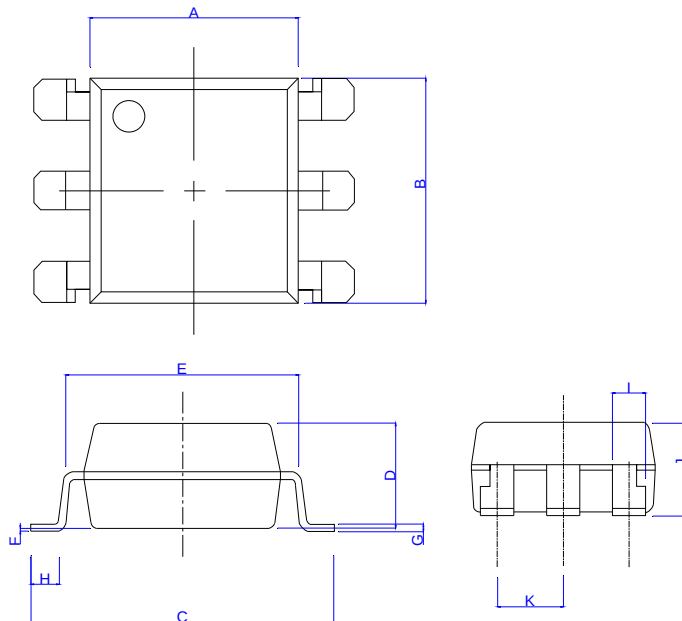




Package Dimension (Unit: mm)



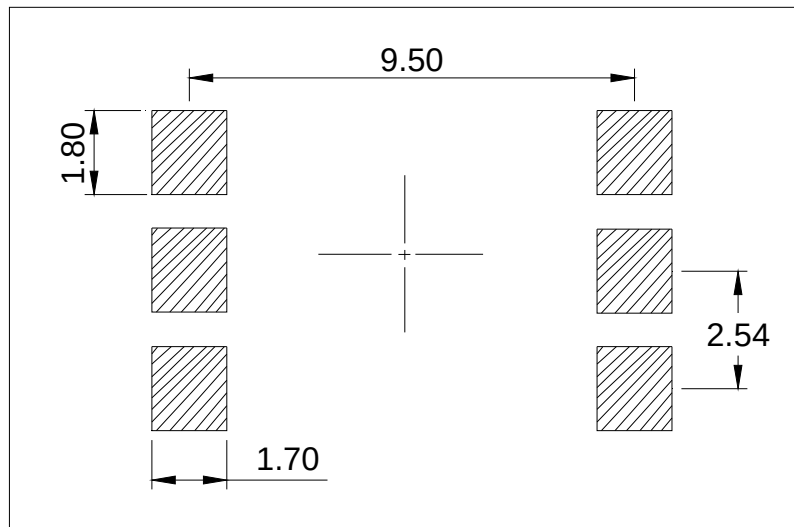
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	6.92		7.32	0.272		0.288
C	7.15		8.95	0.281		0.352
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.15		0.35	0.006		0.014
G	1.15		1.35	0.045		0.053
H	3.90		4.50	0.154		0.177
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.090		0.110
K	2.24		3.24	0.088		0.128



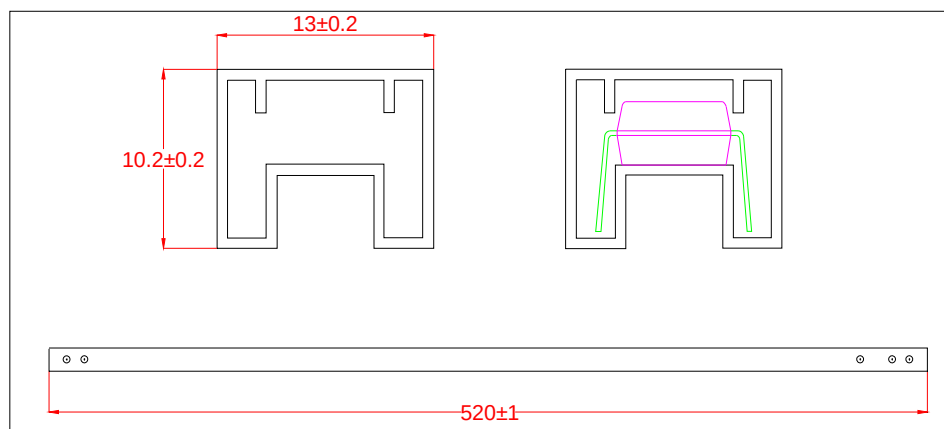
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	6.92		7.32	0.272		0.288
C	9.50		10.50	0.375		0.413
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.05		0.35	0.002		0.014
G	0.16		0.36	0.006		0.014
H	0.60		1.40	0.024		0.055
I	0.90		1.50	0.035		0.059
J	3.30		3.90	0.130		0.154
K	2.29		2.79	0.090		0.110



RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

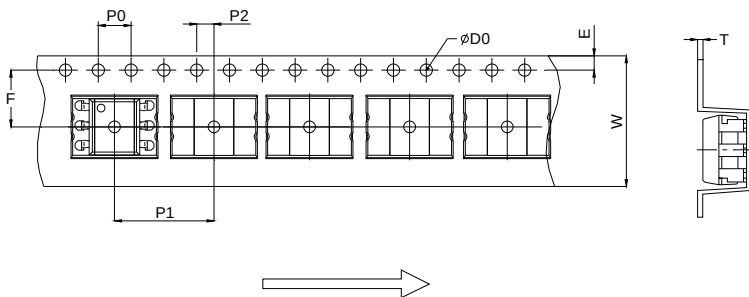


TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

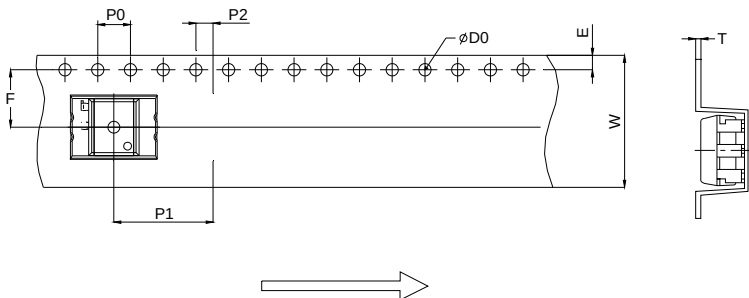




CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)



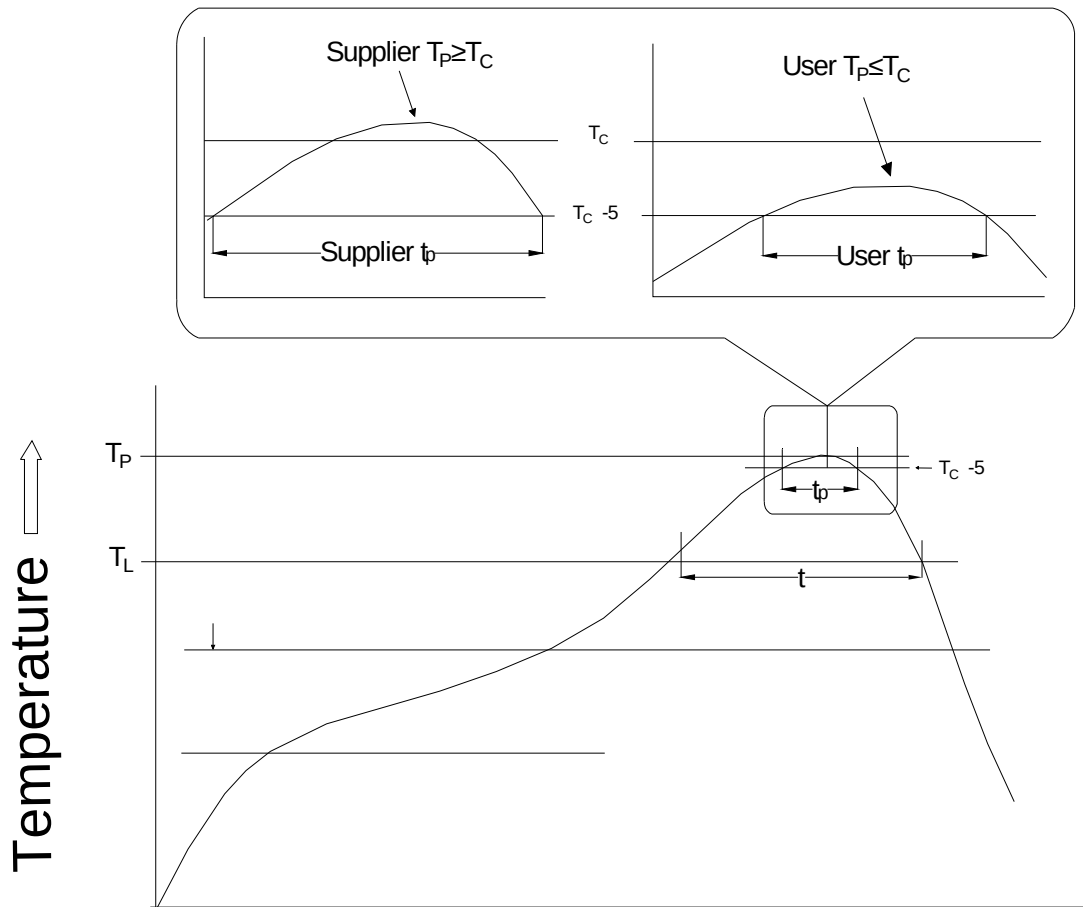
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642

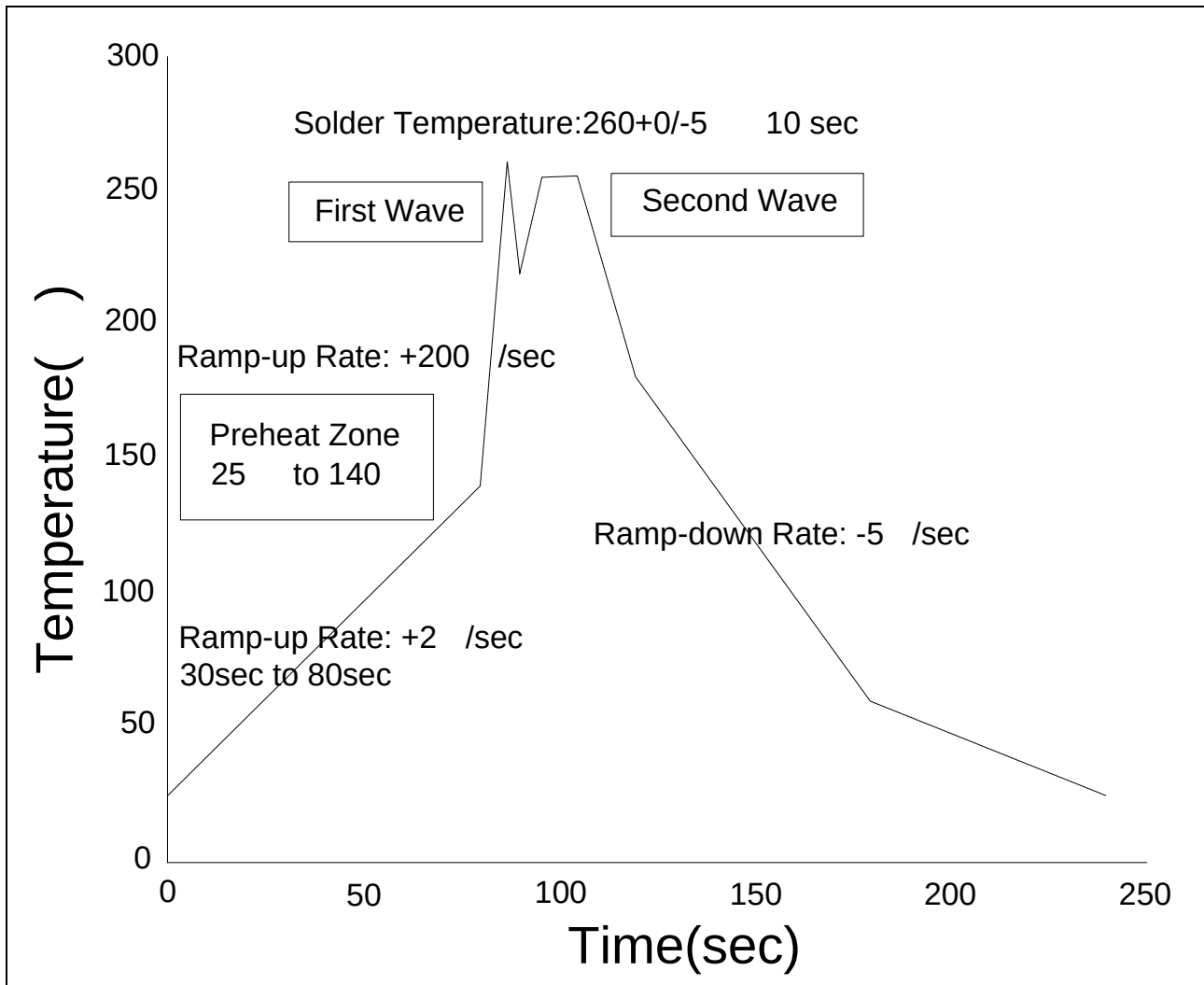


REFLOW INFORMATION





WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON

Soldering Temperature	360 ± 5
Soldering Time	3s max.



Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 1

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